

## CLAIMS

1. A method for manufacturing a printed wiring board,  
comprising the steps of: using a carbon dioxide laser to  
form recess portions such as via holes in a copper clad  
5 laminate; plating said copper clad laminate to form  
interlayer electrical connections forming etching resist  
layers; and exposing and developing the etching resist  
layers, thereby effecting a circuit etching treatment,  
wherein the copper clad laminate is a laminate formed by  
10 using waved copper foils to form external copper foils.
2. A method for manufacturing a printed wiring board  
according to claim 1, wherein each waved copper foil for use  
in forming the external copper foils of the copper clad  
15 laminate includes a bulk copper layer forming a conductor  
circuit of the printed wiring board, an amount of fine  
copper particles for ensuring an adhesion strength between  
the bulk copper layer and a resin substrate, and a rust  
preventive layer, said bulk copper layer having a thickness  
20 of 18  $\mu\text{m}$  or less.
3. A method for manufacturing a printed wiring board  
according to claim 1, wherein each of the waved copper foils  
has a surface roughness (Rz) of 2.0 to 20.0  $\mu\text{m}$ .
- 25 4. New claim added by Preliminary Amendment.